



Semiconductor Device Type: C4X-PDIP-8-.300in-MatteTin						Package Homogeneous Materials				
Sub-Component	Basic Substance	CAS Number	% Total Weight	mg/part	ppm	50.00	(mg) Total	Die	% of Total Weight	9.90
Die	Silicon	7440-21-3	9.90	50.00	99010		Silicon	7440-21-3	100.00	
Plating & Anode Ball	Lead	7439-92-1	0.01	0.07	139	Total 100.00				
Plating & Anode Ball	Tin	7440-31-5	27.71	139.93	277089					
Bonding Wire	Gold	7440-57-5	0.01	0.05	99	140.00	(mg) Total	Plating & Anode Ball	% of Total Weight	27.72
Bonding Wire	Nickel	7440-02-0	0.00	0.03	50		Lead	7439-92-1	0.05	
Bonding Wire	Copper	7440-50-8	0.95	4.77	9455		Tin	7440-31-5	99.95	
Bonding Wire	Palladium	2023568	0.03	0.15	297	Total 100.00				
Mold Compound	Phenolic Resin	Trade Secret	2.97	15.00	29703					
Mold Compound	Carbon Black	1333-86-4	0.30	1.50	2970	5.00	(mg) Total	Bonding Wire	% of Total Weight	0.99
Mold Compound	Other	Trade Secret	1.19	6.00	11881		Gold	7440-57-5	1.00	
Mold Compound	Epoxy Resin	Trade Secret	2.97	15.00	29703		Nickel	7440-02-0	0.50	
Mold Compound	Vitreous silica	60676-86-0	22.28	112.50	222772		Copper	7440-50-8	95.50	
Die Attach Epoxy	Silver	7440-22-4	4.25	21.45	42475		Palladium	2023568	3.00	
Die Attach Epoxy	Formaldehyde, polymer with 2-(chloromethyl)oxirane and phenol	9003-36-5	0.89	4.50	8911	Total 100.00				
Die Attach Epoxy	p-tert-Butylphenyl glycidyl ether	3101-60-8	0.45	2.25	4455					
Die Attach Epoxy	Dicyandiamide	461-58-5	0.06	0.30	594	150.00	(mg) Total	Mold Compound	% of Total Weight	29.70
Die Attach Epoxy	Phenolic Resin	Trade Secret	0.15	0.75	1485		Phenolic Resin	Trade Secret	10.00	
Die Attach Epoxy	Amine	Trade Secret	0.15	0.75	1485		Carbon Black	1333-86-4	1.00	
Lead Frame	Silver	7440-22-4	1.62	8.19	16218		Other	Trade Secret	4.00	
Lead Frame	Copper	7440-50-8	23.41	118.20	234068		Epoxy Resin	Trade Secret	10.00	
Lead Frame	Iron	7439-89-6	0.63	3.17	6271		Vitreous silica	60676-86-0	75.00	
Lead Frame	Lead	7439-92-1	0.00	0.01	24	Total 100.00				
Lead Frame	Phosphorus	7723-14-0	0.04	0.18	362					
Lead Frame	Zinc	7440-66-6	0.05	0.24	482	30.00	(mg) Total	Die Attach Epoxy	% of Total Weight	5.94
TOTALS: 505.00 mg Total Mass			100.00	505.00	1,000,000		Silver	7440-22-4	71.50	
							Formaldehyde, polymer with 2-(chloromethyl)oxirane and phenol	9003-36-5	15.00	
							p-tert-Butylphenyl glycidyl ether	3101-60-8	7.50	
							Dicyandiamide	461-58-5	1.00	
							Phenolic Resin	Trade Secret	2.50	
							Amine	Trade Secret	2.50	
						Total 100.00				
						130.00	(mg) Total	Lead Frame	% of Total Weight	25.74
							Silver	7440-22-4	6.30	
							Copper	7440-50-8	90.93	
							Iron	7439-89-6	2.44	
							Lead	7439-92-1	0.01	
							Phosphorus	7723-14-0	0.14	
							Zinc	7440-66-6	0.19	
						505.00	Total	100.00		100.00

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.

Microchip Technology Incorporated designs all products to comply with global product material compliance standards, including but not limited to RoHS, REACH, and China RoHS. Additionally, Microchip products are designed to be compliant with IEC62474. For specific compliance information, please check our product material compliance website on microchip.com or ask your local sales representative.

Microchip Technology Incorporated believes the information in this MCD is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts. These estimates do not include trace levels of dopants, impurities, metals, and non-metallic materials which may be contained within silicon devices (silicon IC) or the finished parts.

Microchip Technology Incorporated does not provide any warranty, express or implied, with respect to the information provided in this declaration. The exclusive, limited product warranties provided by Microchip Technology Incorporated, and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's quotations, sales order acknowledgements, and invoices.

Microchip disclaims any duty to notify users of updates or changes to MCDs and shall not be liable for any damages, direct or indirect, consequential or otherwise, suffered by users or third parties as a result of the users' reliance on the information in MCDs.